



Application of Hyperspectral Imaging for Nondestructive Measurement

Guest Editor:

Prof. Dr. Byoung-Kwan Cho

Nondestructive Bio-Sensing
Laboratory, Department of
Biosystems Machinery
Engineering, Chungnam National
University, Daejeon 34134, Korea

Deadline for manuscript
submissions:

closed (30 April 2020)

Message from the Guest Editor

Dear Colleagues,

Hyperspectral imaging technology has recently emerged as a powerful analytical technique that uses vibrational spectroscopy for nondestructive quality measurement of various materials. The previously described spectroscopic analytical methods (Vis/NIR, MIR, Fluorescence, Raman spectroscopies, etc.) are well-established, non-invasive analytical techniques for the analysis of materials. However, these techniques are point-based scanning techniques and only examine a relatively small area of a specimen. Sample analysis is also more convenient and fast compared with the hyperspectral imaging technique, instead of the single sampling technique used by the other spectroscopic methods. Furthermore, HSI has instrumental flexibility and can be used to collect hyperspectral data for specimens with different sizes and shapes. With these advantages and flexibility, hyperspectral imaging has been successfully adopted in a variety of research and industry environments. This Special Issue focuses on the latest research and development of hyperspectral imaging in nondestructive measurement applications.

Prof. Dr. Byoung-Kwan Cho
Guest Editor





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Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
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Message from the Editor-in-Chief

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